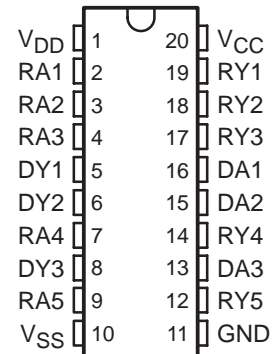


# GD65232, GD75232 MULTIPLE RS-232 DRIVERS AND RECEIVERS

SLLS206J – MAY 1995 – REVISED NOVEMBER 2004

- **Single Chip With Easy Interface Between UART and Serial-Port Connector of IBM™ PC/AT and Compatibles**
- **Meet or Exceed the Requirements of TIA/EIA-232-F and ITU v.28 Standards**
- **Designed to Support Data Rates up to 120 kbit/s**
- **Pinout Compatible With SN75C185 and SN75185**

GD65232, GD75232 . . . DB, DW, N, OR PW PACKAGE  
(TOP VIEW)



## description/ordering information

The GD65232 and GD75232 combine three drivers and five receivers from the Texas Instruments trade-standard SN75188 and SN75189 bipolar quadruple drivers and receivers, respectively. The pinout matches the flow-through design of the SN75C185 to decrease the part count, reduce the board space required, and allow easy interconnection of the UART and serial-port connector of an IBM™ PC/AT and compatibles. The bipolar circuits and processing of the GD65232 and GD75232 provide a rugged, low-cost solution for this function at the expense of quiescent power and external passive components relative to the SN75C185.

The GD65232 and GD75232 comply with the requirements of the TIA/EIA-232-F and ITU (formerly CCITT) V.28 standards. These standards are for data interchange between a host computer and a peripheral at signaling rates up to 20 kbit/s. The switching speeds of these devices are fast enough to support rates up to 120 kbit/s with lower capacitive loads (shorter cables). Interoperability at the higher signaling rates cannot be expected unless the designer has design control of the cable and the interface circuits at both ends. For interoperability at signaling rates up to 120 kbit/s, use of TIA/EIA-423-B (ITU V.10) and TIA/EIA-422-B (ITU V.11) standards is recommended.

## ORDERING INFORMATION

T <sub>A</sub>	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 85°C	PDIP (N)	Tube of 20	GD65232N	GD65232N
	SOIC (DW)	Tube of 25	GD65232DW	GD65232
		Reel of 2000	GD65232DWR	
	SSOP (DB)	Reel of 2000	GD65232DBR	GD65232
TSSOP (PW)	Tube of 70	GD65232PW	GD65232	
	Reel of 2000	GD65232PWR		
0°C to 70°C	PDIP (N)	Tube of 20	GD75232N	GD75232N
	SOIC (DW)	Tube of 25	GD75232DW	GD75232
		Reel of 2000	GD75232DWR	
	SSOP (DB)	Reel of 2000	GD75232DBR	GD75232
	TSSOP (PW)	Tube of 70	GD75232PW	GD75232
		Reel of 2000	GD75232PWR	

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at [www.ti.com/sc/package](http://www.ti.com/sc/package).



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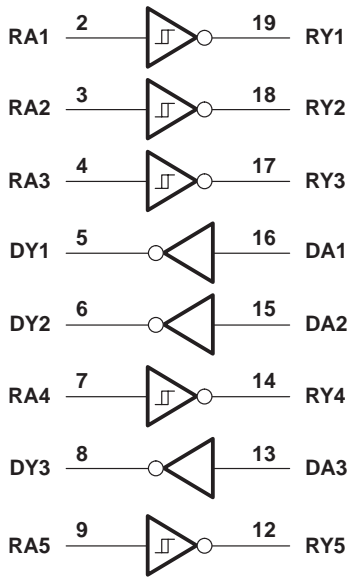


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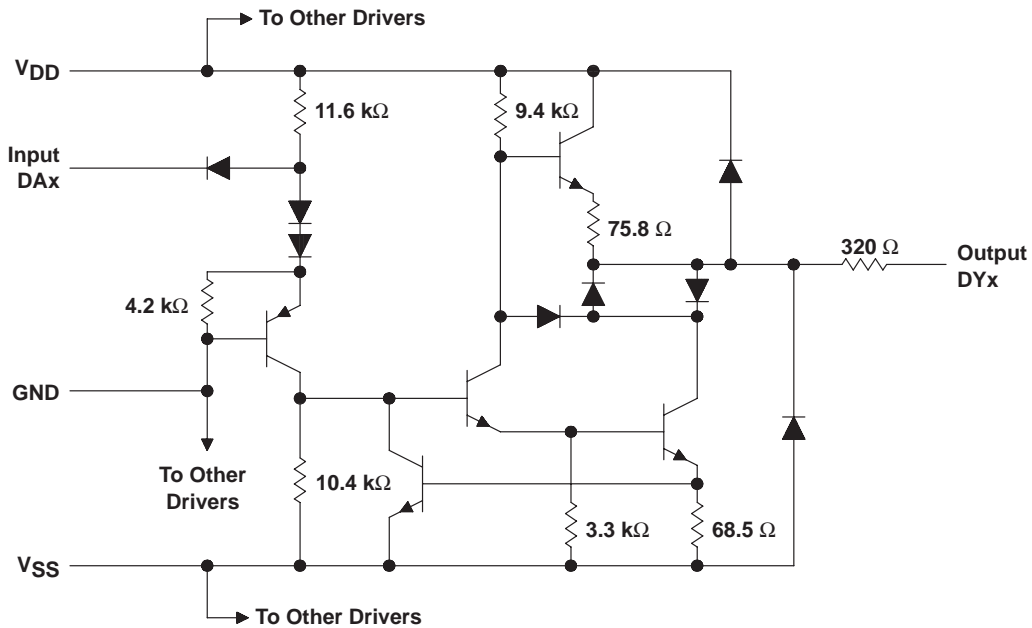
# GD65232, GD75232 MULTIPLE RS-232 DRIVERS AND RECEIVERS

SLLS206J – MAY 1995 – REVISED NOVEMBER 2004

## logic diagram (positive logic)

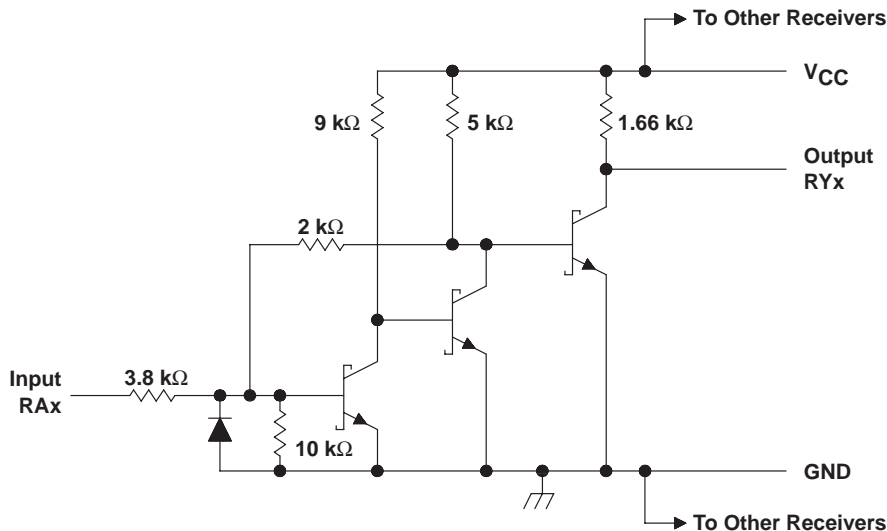


## schematic (each driver)



Resistor values shown are nominal.

**schematic (each receiver)**



Resistor values shown are nominal.

**absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†**

Supply voltage (see Note 1): $V_{CC}$ .....	10 V
$V_{DD}$ .....	15 V
$V_{SS}$ .....	-15 V
Input voltage range, $V_i$ : Driver .....	-15 V to 7 V
Receiver .....	-30 V to 30 V
Driver output voltage range, $V_O$ .....	-15 V to 15 V
Receiver low-level output current, $I_{OL}$ .....	20 mA
Package thermal impedance, $\theta_{JA}$ (see Notes 2 and 3): DB package .....	70°C/W
DW package .....	58°C/W
N package .....	69°C/W
PW package .....	83°C/W
Operating virtual junction temperature, $T_J$ .....	150°C
Storage temperature range, $T_{Stg}$ .....	-65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. All voltages are with respect to the network ground terminal.  
 2. Maximum power dissipation is a function of  $T_J(max)$ ,  $\theta_{JA}$ , and  $T_A$ . The maximum allowable power dissipation at any allowable ambient temperature is  $P_D = (T_J(max) - T_A)/\theta_{JA}$ . Operating at the absolute maximum  $T_J$  of 150°C can affect reliability.  
 3. The package thermal impedance is calculated in accordance with JESD 51-7.

# GD65232, GD75232

## MULTIPLE RS-232 DRIVERS AND RECEIVERS

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### recommended operating conditions

		MIN	NOM	MAX	UNIT
V <sub>DD</sub>	Supply voltage (see Note 4)	7.5	9	15	V
V <sub>SS</sub>	Supply voltage (see Note 4)	-7.5	-9	-15	V
V <sub>CC</sub>	Supply voltage (see Note 4)	4.5	5	5.5	V
V <sub>IH</sub>	High-level input voltage (driver only)	1.9			V
V <sub>IL</sub>	Low-level input voltage (driver only)			0.8	V
I <sub>OH</sub>	High-level output current	Driver		-6	mA
		Receiver		-0.5	
I <sub>OL</sub>	Low-level output current	Driver		6	mA
		Receiver		16	
T <sub>A</sub>	Operating free-air temperature	GD65232	-40	85	°C
		GD75232	0	70	

NOTE 4: When powering up the GD65232 and GD75232, the following sequence should be used:

1. V<sub>SS</sub>
2. V<sub>DD</sub>
3. V<sub>CC</sub>
4. I/Os

Applying V<sub>CC</sub> before V<sub>DD</sub> may allow large currents to flow, causing damage to the device. When powering down the GD65232 and GD75232, the reverse sequence should be used.

### supply currents over recommended operating free-air temperature range

PARAMETER	TEST CONDITIONS		MIN	MAX	UNIT
I <sub>DD</sub> Supply current from V <sub>DD</sub>	All inputs at 1.9 V, No load	V <sub>DD</sub> = 9 V, V <sub>SS</sub> = -9 V		15	mA
		V <sub>DD</sub> = 12 V, V <sub>SS</sub> = -12 V		19	
		V <sub>DD</sub> = 15 V, V <sub>SS</sub> = -15 V		25	
	All inputs at 0.8 V, No load	V <sub>DD</sub> = 9 V, V <sub>SS</sub> = -9 V		4.5	
		V <sub>DD</sub> = 12 V, V <sub>SS</sub> = -12 V		5.5	
		V <sub>DD</sub> = 15 V, V <sub>SS</sub> = -15 V		9	
I <sub>SS</sub> Supply current from V <sub>SS</sub>	All inputs at 1.9 V, No load	V <sub>DD</sub> = 9 V, V <sub>SS</sub> = -9 V		-15	mA
		V <sub>DD</sub> = 12 V, V <sub>SS</sub> = -12 V		-19	
		V <sub>DD</sub> = 15 V, V <sub>SS</sub> = -15 V		-25	
	All inputs at 0.8 V, No load	V <sub>DD</sub> = 9 V, V <sub>SS</sub> = -9 V		-3.2	
		V <sub>DD</sub> = 12 V, V <sub>SS</sub> = -12 V		-3.2	
		V <sub>DD</sub> = 15 V, V <sub>SS</sub> = -15 V		-3.2	
I <sub>CC</sub> Supply current from V <sub>CC</sub>	All inputs at 5 V, No load, V <sub>CC</sub> = 5 V	GD65232		38	mA
		GD75232		30	



**DRIVER SECTION**

**electrical characteristics over recommended operating free-air temperature range,  $V_{DD} = 9\text{ V}$ ,  $V_{SS} = -9\text{ V}$ ,  $V_{CC} = 5\text{ V}$  (unless otherwise noted)**

PARAMETER		TEST CONDITIONS			MIN	TYP	MAX	UNIT
$V_{OH}$	High-level output voltage	$V_{IL} = 0.8\text{ V}$ ,	$R_L = 3\text{ k}\Omega$ ,	See Figure 1	6	7.5		V
$V_{OL}$	Low-level output voltage (see Note 5)	$V_{IH} = 1.9\text{ V}$ ,	$R_L = 3\text{ k}\Omega$ ,	See Figure 1		-7.5	-6	V
$I_{IH}$	High-level input current	$V_I = 5\text{ V}$ ,	See Figure 2				10	$\mu\text{A}$
$I_{IL}$	Low-level input current	$V_I = 0$ ,	See Figure 2				-1.6	mA
$I_{OS(H)}$	High-level short-circuit output current (see Note 6)	$V_{IL} = 0.8\text{ V}$ ,	$V_O = 0$ ,	See Figure 1	-4.5	-12	-19.5	mA
$I_{OS(L)}$	Low-level short-circuit output current	$V_{IH} = 2\text{ V}$ ,	$V_O = 0$ ,	See Figure 1	4.5	12	19.5	mA
$r_o$	Output resistance (see Note 7)	$V_{CC} = V_{DD} = V_{SS} = 0$ ,		$V_O = -2\text{ V to } 2\text{ V}$	300			$\Omega$

- NOTES: 5. The algebraic convention, where the more positive (less negative) limit is designated as maximum, is used in this data sheet for logic levels only (e.g., if  $-10\text{ V}$  is maximum, the typical value is a more negative voltage).  
6. Output short-circuit conditions must maintain the total power dissipation below absolute maximum ratings.  
7. Test conditions are those specified by TIA/EIA-232-F and as listed above.

**switching characteristics,  $V_{CC} = 5\text{ V}$ ,  $V_{DD} = 12\text{ V}$ ,  $V_{SS} = -12\text{ V}$ ,  $T_A = 25^\circ\text{C}$**

PARAMETER		TEST CONDITIONS			MIN	TYP	MAX	UNIT
$t_{PLH}$	Propagation delay time, low- to high-level output	$R_L = 3\text{ k}\Omega$ to $7\text{ k}\Omega$ ,	$C_L = 15\text{ pF}$ ,	See Figure 3		315	500	ns
$t_{PHL}$	Propagation delay time, high- to low-level output	$R_L = 3\text{ k}\Omega$ to $7\text{ k}\Omega$ ,	$C_L = 15\text{ pF}$ ,	See Figure 3		75	175	ns
$t_{TLH}$	Transition time, low- to high-level output	$R_L = 3\text{ k}\Omega$ to $7\text{ k}\Omega$	$C_L = 15\text{ pF}$ ,	See Figure 3		60	100	ns
			$C_L = 2500\text{ pF}$ ,	See Figure 3 and Note 8		1.7	2.5	$\mu\text{s}$
$t_{THL}$	Transition time, high- to low-level output	$R_L = 3\text{ k}\Omega$ to $7\text{ k}\Omega$	$C_L = 15\text{ pF}$ ,	See Figure 3		40	75	ns
			$C_L = 2500\text{ pF}$ ,	See Figure 3 and Note 8		1.5	2.5	$\mu\text{s}$

NOTE 8: Measured between  $\pm 3\text{-V}$  and  $\pm 3\text{-V}$  points of the output waveform (TIA/EIA-232-F conditions); all unused inputs are tied either high or low.

# GD65232, GD75232 MULTIPLE RS-232 DRIVERS AND RECEIVERS

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## RECEIVER SECTION

### electrical characteristics over recommended operating conditions (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP†	MAX	UNIT
V <sub>IT+</sub>	Positive-going input threshold voltage	T <sub>A</sub> = 25°C,	See Figure 5	1.75	1.9	2.3	V
		T <sub>A</sub> = 0°C to 70°C,	See Figure 5	1.55		2.3	
V <sub>IT-</sub>	Negative-going input threshold voltage			0.75	0.97	1.25	V
V <sub>hys</sub>	Input hysteresis voltage (V <sub>IT+</sub> - V <sub>IT-</sub> )			0.5			V
V <sub>OH</sub>	High-level output voltage	I <sub>OH</sub> = -0.5 mA	V <sub>IH</sub> = 0.75 V	2.6	4	5	V
			Inputs open	2.6			
V <sub>OL</sub>	Low-level output voltage	I <sub>OL</sub> = 10 mA,	V <sub>I</sub> = 3 V		0.2	0.45	V
I <sub>IH</sub>	High-level input current	V <sub>I</sub> = 25 V,	See Figure 5	GD65232	3.6	11	mA
				GD75232	3.6	8.3	
		V <sub>I</sub> = 3 V,	See Figure 5		0.43		
I <sub>IL</sub>	Low-level input current	V <sub>I</sub> = -25 V,	See Figure 5	GD65232	-3.6	-11	mA
				GD75232	-3.6	-8.3	
		V <sub>I</sub> = -3 V,	See Figure 5		-0.43		
I <sub>OS</sub>	Short-circuit output current	See Figure 4			-3.4	-12	mA

† All typical values are at T<sub>A</sub> = 25°C, V<sub>CC</sub> = 5 V, V<sub>DD</sub> = 9 V, and V<sub>SS</sub> = -9 V.

### switching characteristics, V<sub>CC</sub> = 5 V, V<sub>DD</sub> = 12 V, V<sub>SS</sub> = -12 V, T<sub>A</sub> = 25°C

PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT
t <sub>PLH</sub>	Propagation delay time, low- to high-level output	C <sub>L</sub> = 50 pF, R <sub>L</sub> = 5 kΩ, See Figure 6			107	250	ns
t <sub>PHL</sub>	Propagation delay time, high- to low-level output				42	150	ns
t <sub>TLH</sub>	Transition time, low- to high-level output				175	350	ns
t <sub>THL</sub>	Transition time, high- to low-level output				16	60	ns
t <sub>PLH</sub>	Propagation delay time, low- to high-level output	C <sub>L</sub> = 15 pF, R <sub>L</sub> = 1.5 kΩ, See Figure 6			100	160	ns
t <sub>PHL</sub>	Propagation delay time, high- to low-level output				60	100	ns
t <sub>TLH</sub>	Transition time, low- to high-level output				90	175	ns
t <sub>THL</sub>	Transition time, high- to low-level output				15	50	ns



PARAMETER MEASUREMENT INFORMATION

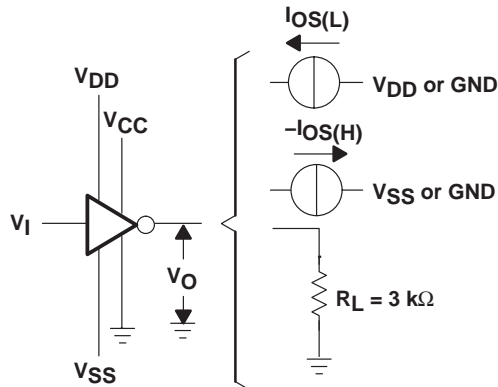


Figure 1. Driver Test Circuit for  $V_{OH}$ ,  $V_{OL}$ ,  $I_{OS(H)}$ , and  $I_{OS(L)}$

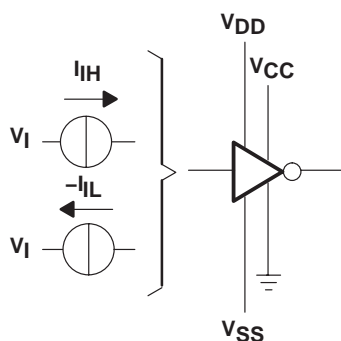
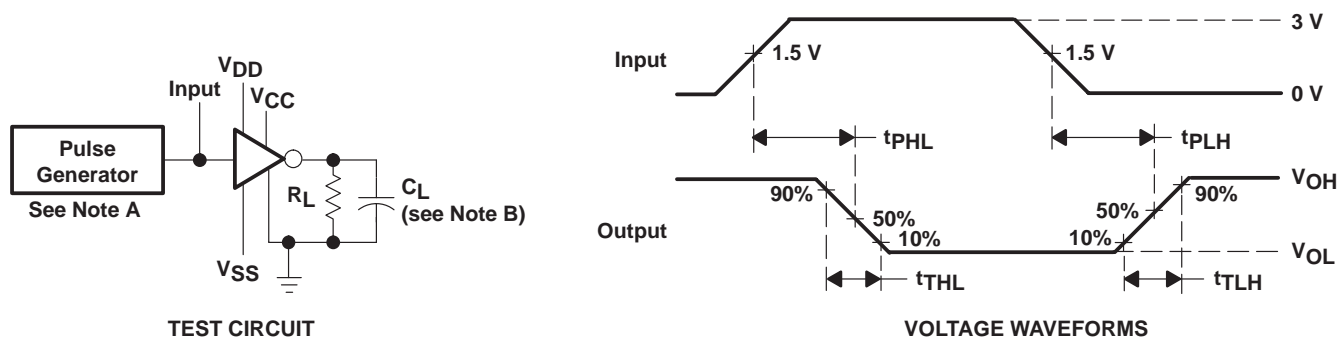


Figure 2. Driver Test Circuit for  $I_{IH}$  and  $I_{IL}$



NOTES: A. The pulse generator has the following characteristics:  $t_w = 25\ \mu\text{s}$ ,  $\text{PRR} = 20\ \text{kHz}$ ,  $Z_O = 50\ \Omega$ ,  $t_r = t_f < 50\ \text{ns}$ .  
 B.  $C_L$  includes probe and jig capacitance.

Figure 3. Driver Test Circuit and Voltage Waveforms

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## PARAMETER MEASUREMENT INFORMATION

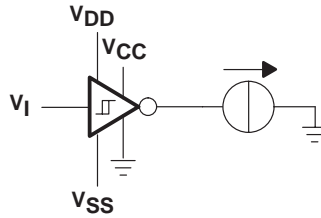


Figure 4. Receiver Test Circuit for  $I_{0S}$

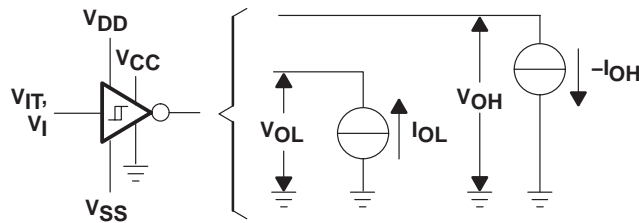
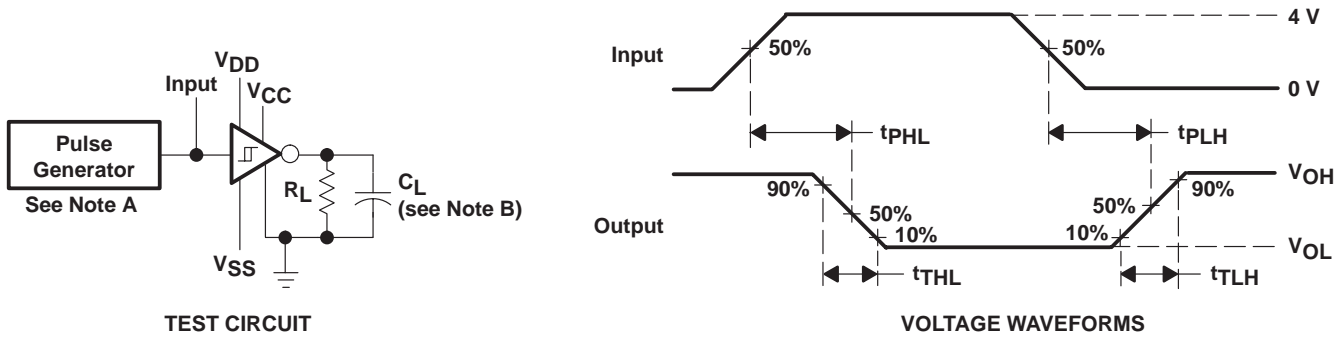


Figure 5. Receiver Test Circuit for  $V_{IT}$ ,  $V_{OH}$ , and  $V_{OL}$



NOTES: A. The pulse generator has the following characteristics:  $t_w = 25 \mu s$ ,  $PRR = 20 \text{ kHz}$ ,  $Z_O = 50 \Omega$ ,  $t_r = t_f < 50 \text{ ns}$ .  
B.  $C_L$  includes probe and jig capacitance.

Figure 6. Receiver Propagation and Transition Times

TYPICAL CHARACTERISTICS

DRIVER SECTION

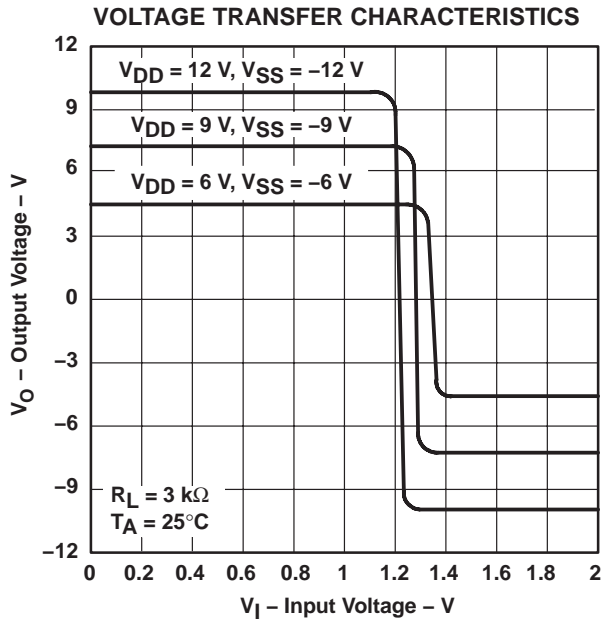


Figure 7

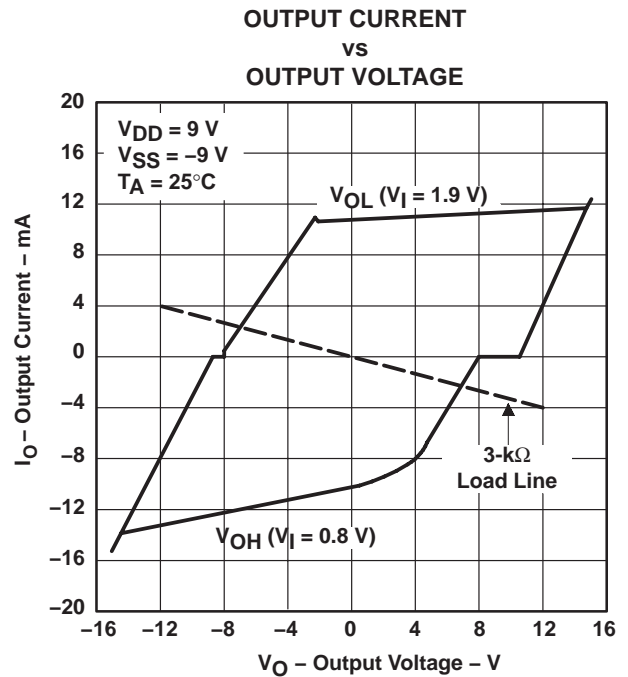


Figure 8

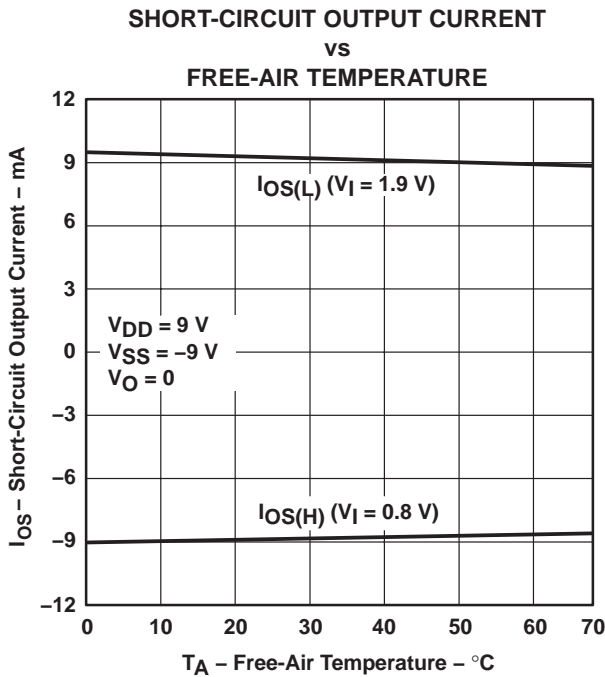


Figure 9

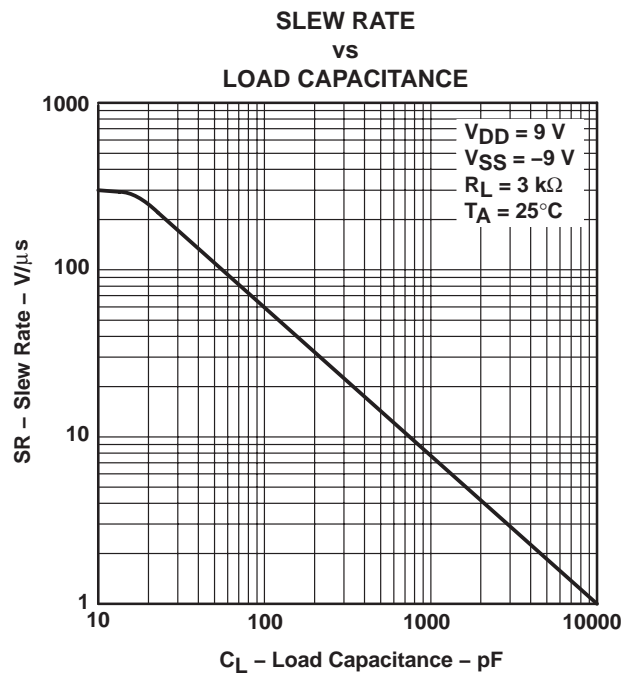
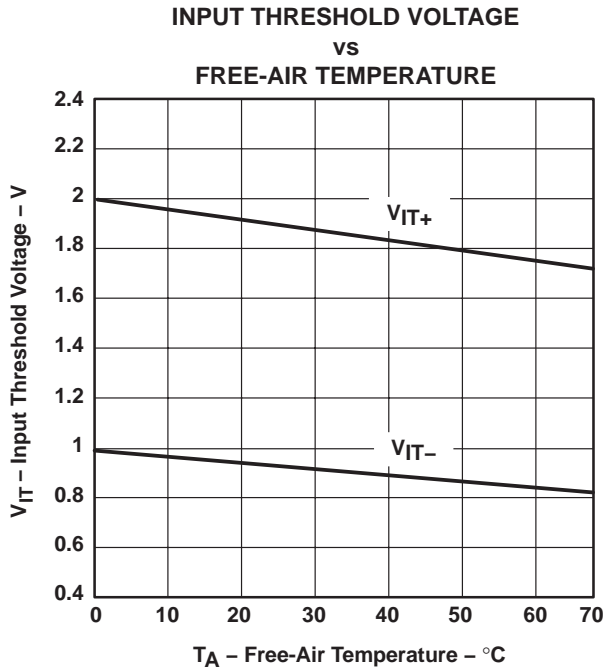
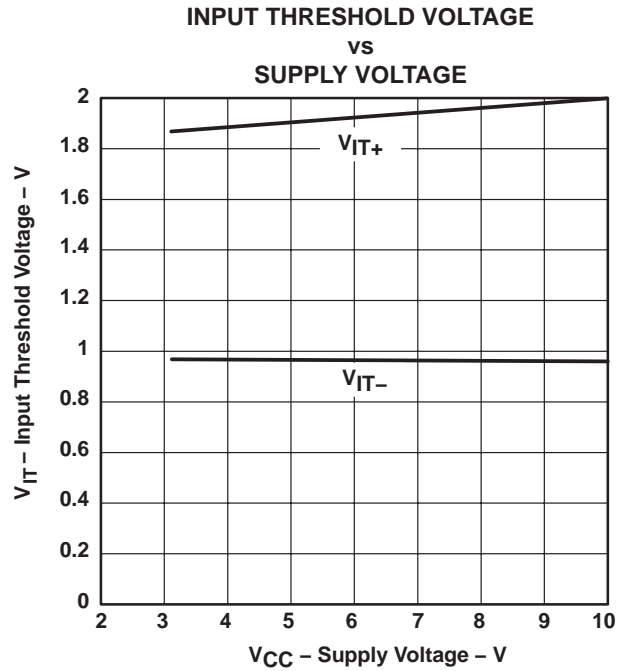


Figure 10

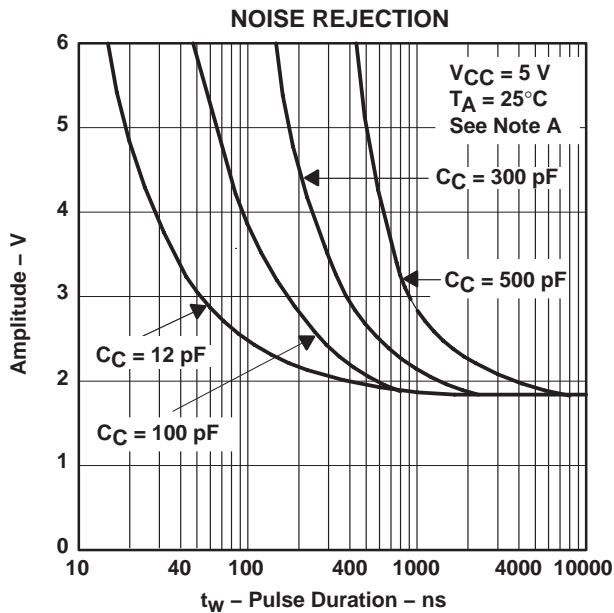
**TYPICAL CHARACTERISTICS**



**Figure 11**

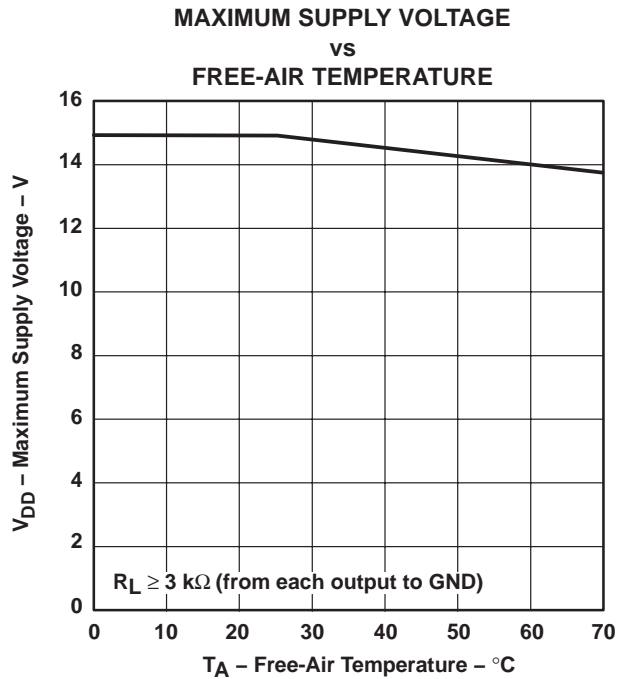


**Figure 12**



NOTE A: This figure shows the maximum amplitude of a positive-going pulse that, starting from 0 V, does not cause a change of the output level.

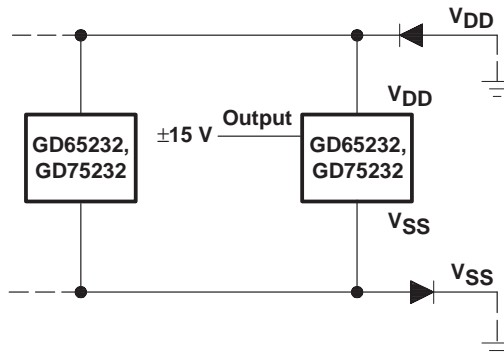
**Figure 13**



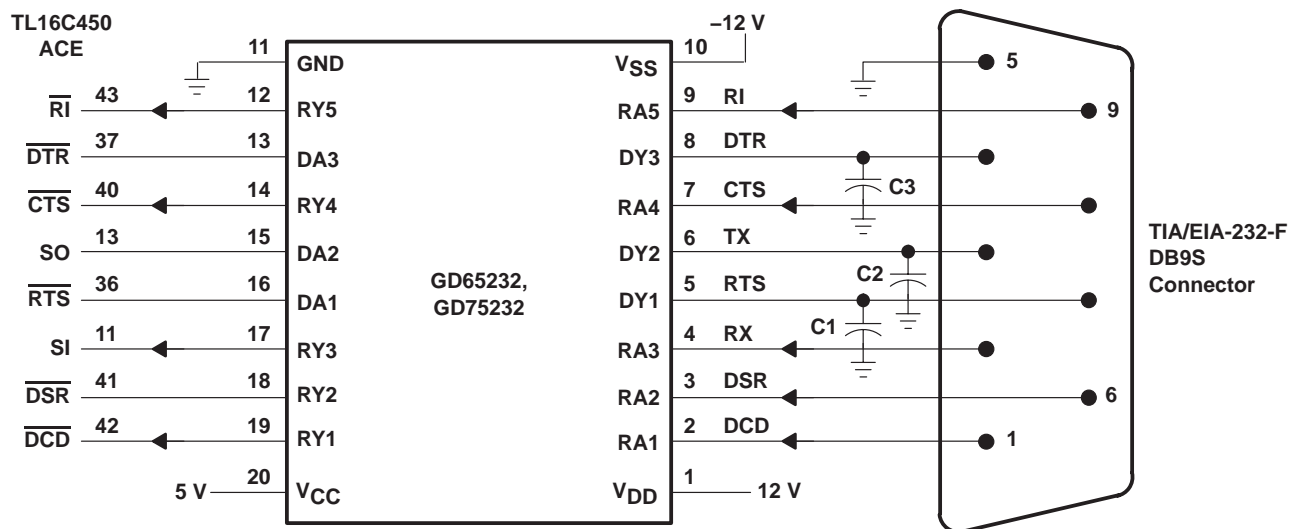
**Figure 14**

**APPLICATION INFORMATION**

Diodes placed in series with the  $V_{DD}$  and  $V_{SS}$  leads protect the GD65232 and GD75232 in the fault condition in which the device outputs are shorted to  $\pm 15$  V and the power supplies are at low and provide low-impedance paths to ground (see Figure 15).



**Figure 15. Power-Supply Protection to Meet Power-Off Fault Conditions of TIA/EIA-232-F**



**Figure 16. Typical Connection**

**PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/ Ball Finish	MSL Peak Temp <sup>(3)</sup>	Samples (Requires Login)
GD65232DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
GD65232DWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
GD65232DWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
GD65232DWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
GD65232DWRE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
GD65232DWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
GD65232PWR	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
GD65232PWRE4	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
GD65232PWRG4	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
GD75232DBR	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
GD75232DBRE4	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
GD75232DBRG4	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
GD75232DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
GD75232DWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
GD75232DWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
GD75232DWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
GD75232DWRE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/ Ball Finish	MSL Peak Temp <sup>(3)</sup>	Samples (Requires Login)
GD75232DWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
GD75232N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
GD75232NE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
GD75232PW	ACTIVE	TSSOP	PW	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
GD75232PWE4	ACTIVE	TSSOP	PW	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
GD75232PWG4	ACTIVE	TSSOP	PW	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
GD75232PWR	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
GD75232PWRE4	ACTIVE	TSSOP	PW	20		Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
GD75232PWRG4	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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**TAPE AND REEL INFORMATION**
**REEL DIMENSIONS**

**TAPE DIMENSIONS**


A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

**TAPE AND REEL INFORMATION**

\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
GD65232DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.0	2.7	12.0	24.0	Q1
GD65232PWR	TSSOP	PW	20	2000	330.0	16.4	6.95	7.1	1.6	8.0	16.0	Q1
GD75232DBR	SSOP	DB	20	2000	330.0	16.4	8.2	7.5	2.5	12.0	16.0	Q1
GD75232DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.0	2.7	12.0	24.0	Q1
GD75232PWR	TSSOP	PW	20	2000	330.0	16.4	6.95	7.1	1.6	8.0	16.0	Q1
GD75232PWR	TSSOP	PW	20	2000	330.0	16.4	6.95	7.1	1.6	8.0	16.0	Q1
GD75232PWRG4	TSSOP	PW	20	2000	330.0	16.4	6.95	7.1	1.6	8.0	16.0	Q1

**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
GD65232DWR	SOIC	DW	20	2000	367.0	367.0	45.0
GD65232PWR	TSSOP	PW	20	2000	367.0	367.0	38.0
GD75232DBR	SSOP	DB	20	2000	367.0	367.0	38.0
GD75232DWR	SOIC	DW	20	2000	367.0	367.0	45.0
GD75232PWR	TSSOP	PW	20	2000	367.0	367.0	38.0
GD75232PWR	TSSOP	PW	20	2000	364.0	364.0	27.0
GD75232PWRG4	TSSOP	PW	20	2000	367.0	367.0	38.0

N (R-PDIP-T\*\*)

PLASTIC DUAL-IN-LINE PACKAGE

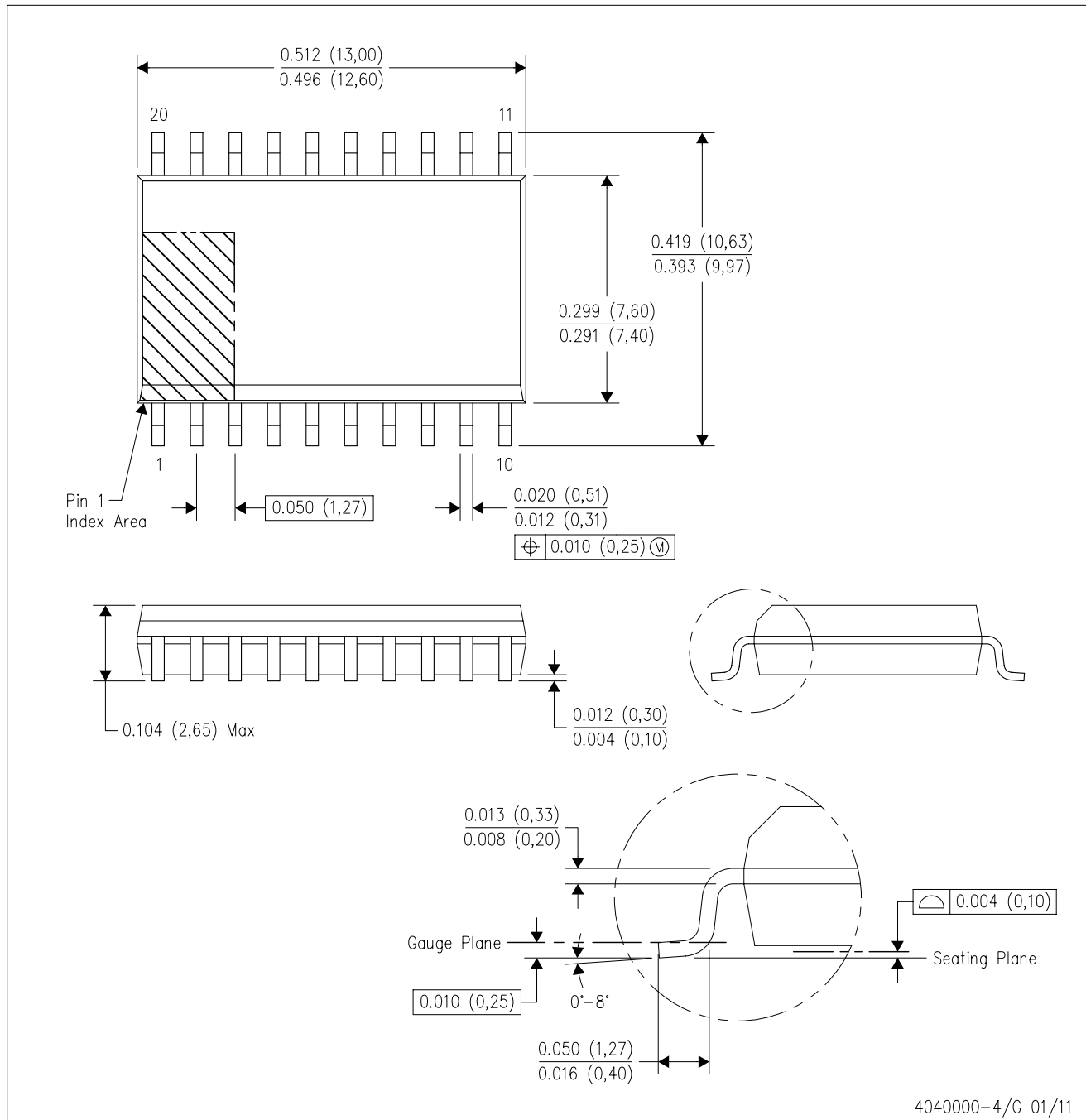
16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
  - The 20 pin end lead shoulder width is a vendor option, either half or full width.

DW (R-PDSO-G20)

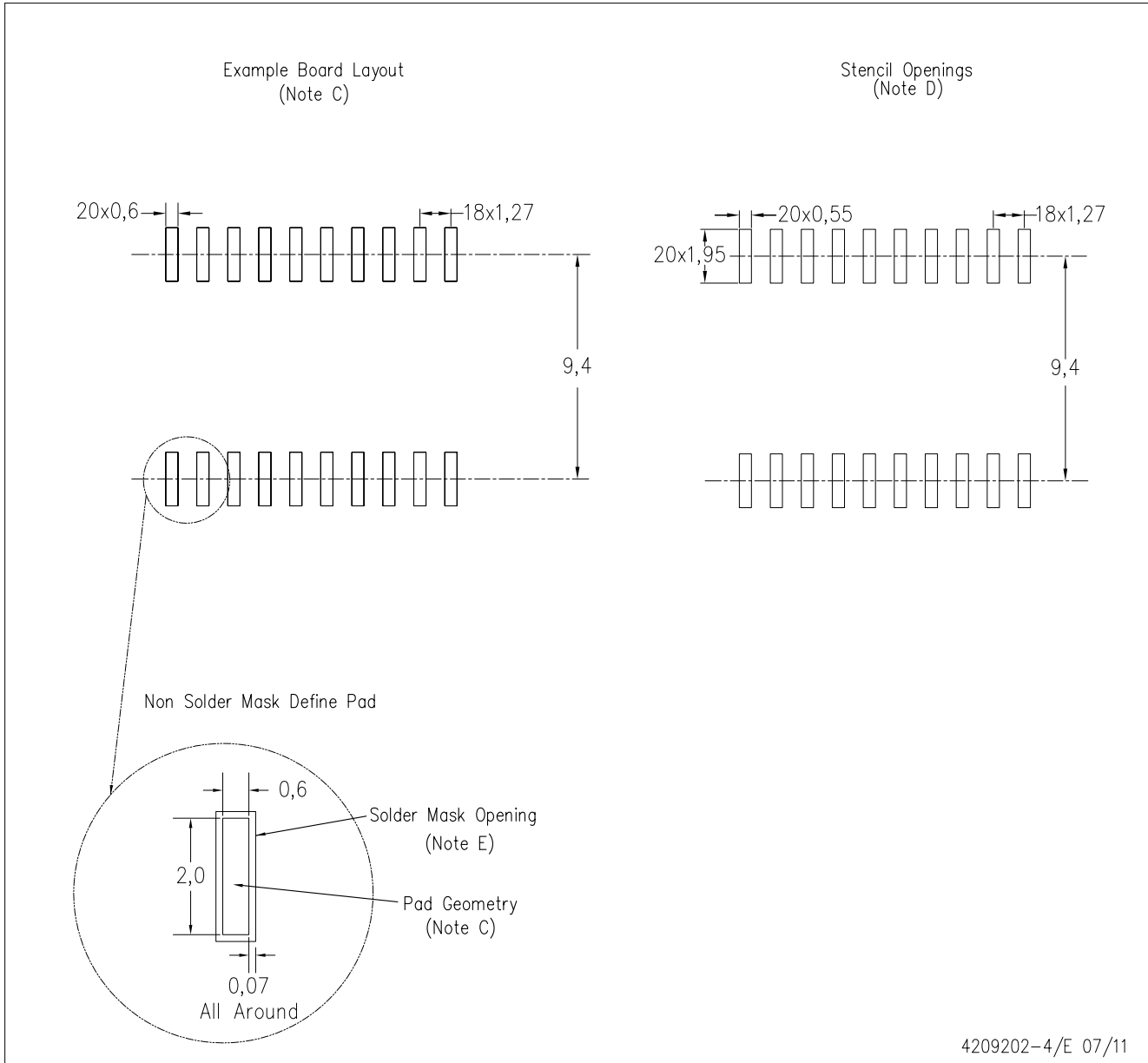
PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
  - D. Falls within JEDEC MS-013 variation AC.

DW (R-PDSO-G20)

PLASTIC SMALL OUTLINE



4209202-4/E 07/11

- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Refer to IPC7351 for alternate board design.
  - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525
  - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

PW (R-PDSO-G20)

PLASTIC SMALL OUTLINE

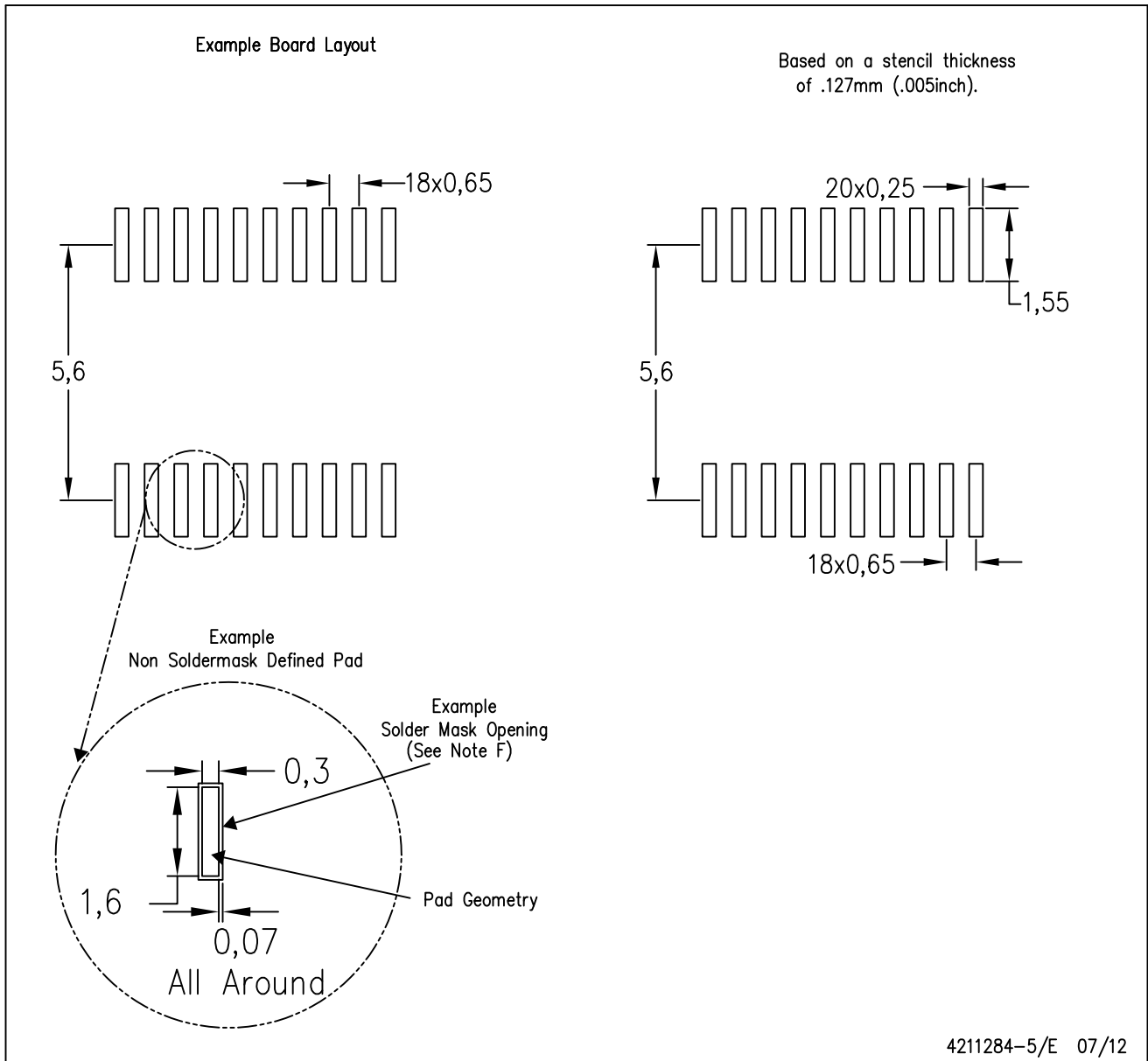


4040064-5/G 02/11

- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
  - B. This drawing is subject to change without notice.
  - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
  - D. Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
  - E. Falls within JEDEC MO-153

PW (R-PDSO-G20)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Publication IPC-7351 is recommended for alternate design.
  - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
  - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

DB (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.  
 D. Falls within JEDEC MO-150

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